DABiC-IV, 20-BIT SERIAL-INPUT, LATCHED SOURCE DRIVER

The A6812– devices combine a 20-bit CMOS shift register, accompanying data latches and control circuitry with bipolar sourcing outputs and pnp active pull downs. Designed primarily to drive vacuum-fluorescent displays, the 60 V and -40 mA output ratings also allow these devices to be used in many other peripheral power driver applications. The A6812– features an increased data input rate (compared with the older UCN/UCQ5812-F) and a controlled output slew rate.

The CMOS shift register and latches allow direct interfacing with microprocessor-based systems. With a 3.3 V or 5 V logic supply, they will operate to at least 10 MHz.

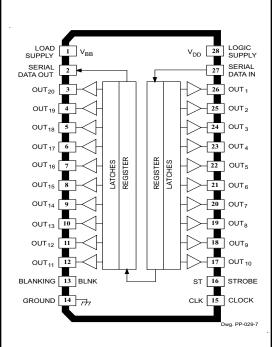
A CMOS serial data output permits cascade connections in applications requiring additional drive lines. Similar devices are available as the A6810– (10 bits) and A6818– (32 bits).

The A6812– output source drivers are npn Darlingtons, capable of sourcing up to 40 mA. The controlled output slew rate reduces electromagnetic noise, which is an important consideration in systems that include telecommunications and/or microprocessors and to meet government emissions regulations. For inter-digit blanking, all output drivers can be disabled and all sink drivers turned on with a BLANKING input high. The pnp active pull-downs will sink at least 2.5 mA.

Three temperature ranges are available for optimum performance in commercial (suffix S-), industrial (suffix E-), or automotive (suffix K-) applications. Package styles are provided for surface-mount SOIC (suffix -LW), or minimum-area surface-mount PLCC (suffix -EP). Copper lead frames, low logic-power dissipation, and low output-saturation voltages allow these drivers to source 25 mA from all outputs continuously to more than +43°C (suffix -LW) or +61°C (suffix -EP).

Each package is available in a lead (Pb) free version, with 100% matte tin leadframe plating.

A6812xLW (SOIC)



ABSOLUTE MAXIMUM RATINGS at $T_A = 25$ °C

701/

Logic Supply Voltage, V _{DD}
Driver Supply Voltage, V _{BB} 60 V
Continuous Output Current Range,
I _{OUT} 40 mA to +15 mA
Input Voltage Range,
V_{IN} 0.3 V to V_{DD} + 0.3 V
Package Power Dissipation,
P _D See Graph
On a section of Tanana a sections Decreased T
Operating Temperature Range, T _A
(Suffix 'E–')40°C to +85°C
(Suffix 'E-')40°C to +85°C
(Suffix 'E–')40°C to +85°C (Suffix 'K–')40°C to +125°C

Caution: These CMOS devices have input static protection (Class 2) but are still susceptible to damage if exposed to extremely high static electrical charges.

FEATURES

- Controlled Output Slew Rate
- High-Speed Data Storage
- 60 V Minimum Output Breakdown
- High Data Input Rate
- PNP Active Pull-Downs
- Low Output-Saturation Voltages
- Low-Power CMOS Logic and Latches
- Improved Replacements for TL5812–, UCN5812–, and UCQ5812–



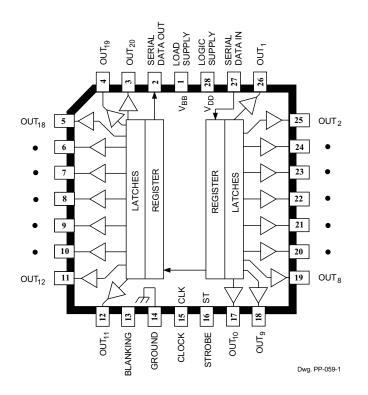


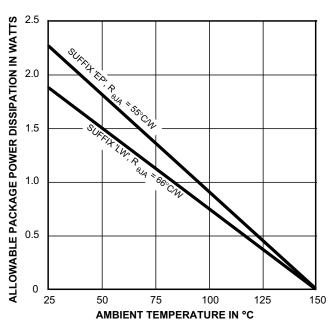
PRODUCT SELECTION GUIDE

Part Number	Pb-free	Packing	Package	Ambient Temperature, T _A (°C)				
A6812EEP	_	20 pieces/tube		-40 to 85				
A6812EEP-T	Yes	38 pieces/tube	PLCC					
A6812EEPTR	_	900 pigggg/12 in root	- PLCC					
A6812EEPTR-T	Yes	800 pieces/13-in. reel						
A6812ELW	_	27 nices 2 /tube						
A6812ELW-T	Yes	27 pieces/tube	COIC W					
A6812ELWTR	_	1000 pigggg/12 in root	SOIC-W					
A6812ELWTR-T	Yes	1000 pieces/13-in. reel						
A6812KEP	_	20 nices // // he						
A6812KEP-T	Yes	38 pieces/tube	DI CC					
A6812KEPTR	_	900 pigggg/12 in root	PLCC					
A6812KEPTR-T	Yes	800 pieces/13-in. reel		-40 to 125				
A6812KLW	_	27 nices 2 /tube		-40 to 125				
A6812KLW-T	Yes	27 pieces/tube	SOIC-W					
A6812KLWTR	_	1000 pigggg/12 in root	3010-77					
A6812KLWTR-T	Yes	1000 pieces/13-in. reel						
A6812SEP	_	20 pieces/tube						
A6812SEP-T	Yes	38 pieces/tube	PLCC					
A6812SEPTR	_	900 pigggg/12 in real	PLCC					
A6812SEPTR-T	Yes	800 pieces/13-in. reel		-20 to 85				
A6812SLW	_	27 pieces/tube		-20 (0 65				
A6812SLW-T	Yes	27 pieces/tube	SOIC-W					
A6812SLWTR	_	1000 pieces/13-in. reel	3010-99					
A6812SLWTR-T	Yes	1000 pieces/13-iii. ieei						



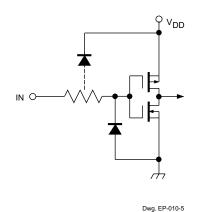
A6812xEP (PLCC)



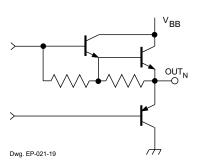


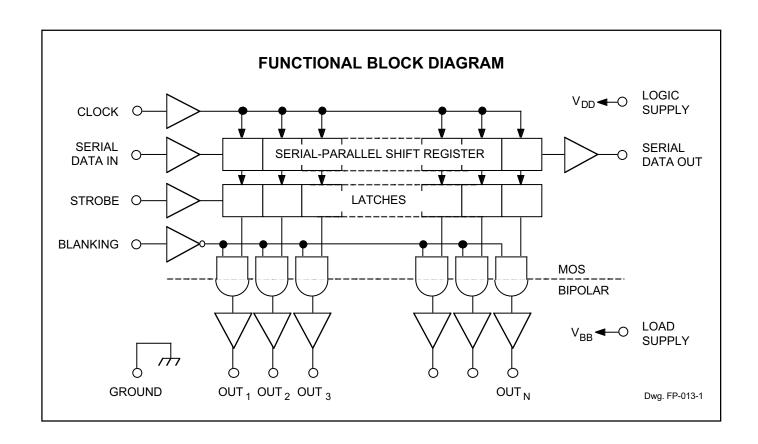
Dwg. GP-024-2

TYPICAL INPUT CIRCUIT



TYPICAL OUTPUT DRIVER





TRUTH TABLE

Serial			hift l	Regi	ster	Conte	ents	Serial			Lat	ch C	onte	ents			Output Contents				5	
Data Input	Clock Input		l ₂	l ₃		I _{N-1}	I _N	Data Output	Strobe Input	l ₁ l ₂ l ₃ l _{N-1}		I _{N-1}	I _N	Blanking	I ₁	l ₂	l ₃		I _{N-1}			
ıN	丁																					
Н	7	Н	R ₁	R ₂		R _{N-2}	R _{N-1}	R _{N-1}														
L	L	L	R ₁	R ₂		R _{N-2}	R _{N-1}	R _{N-1}														
Х		R ₁	R ₂	R ₃		R _{N-1}	R _N	R _N														
		Х	Χ	Х		Х	Х	Х	L	R ₁	R ₂	R ₃		R _{N-1}	R_N							
		P_1	P ₂	P ₃		P _{N-1}	P_{N}	PN	Н	P ₁	P ₂	P ₃	•••	P _{N-1}	P_{N}	L	Ρ ₁	P ₂	P ₃		P _{N-1}	P _N

L = Low Logic Level H = High Logic Level X = Irrelevant P = Present State R = Previous State



ELECTRICAL CHARACTERISTICS at T_A = +25°C (A6812S-) or over operating temperature range (A6812E- or A6812K-), V_{BB} = 60 V unless otherwise noted.

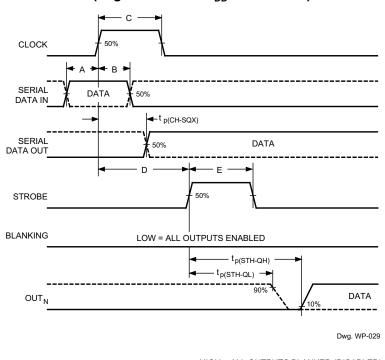
			Limits	@ V _{DD} :	= 3.3 V	Limits			
Characteristic	Symbol	Test Conditions	MIn.	Тур.	Max.	Min.	Тур.	Max.	Units
Output Leakage Current	I _{CEX}	V _{OUT} = 0 V	_	<-0.1	-15	_	<-0.1	-15	μΑ
Output Voltage	V _{OUT(1)}	I _{OUT} = -25 mA	57.5	58.3	_	57.5	58.3	_	V
	V _{OUT(0)}	I _{OUT} = 1 mA	_	1.0	1.5	_	1.0	1.5	V
Output Pull-Down Current	I _{OUT(0)}	V _{OUT} = 5 V to V _{BB}	2.5	5.0	_	2.5	5.0	_	mA
Input Voltage	V _{IN(1)}		2.2	_	_	3.3	_	_	V
	V _{IN(0)}		_	_	1.1	_	_	1.7	V
Input Current	I _{IN(1)}	V _{IN} = V _{DD}	_	<0.01	1.0	_	<0.01	1.0	μΑ
	I _{IN(0)}	V _{IN} = 0 V		<-0.01	-1.0	_	<-0.01	-1.0	μΑ
Input Clamp Voltage	V _{IK}	I _{IN} = -200 μA	_	-0.8	-1.5	_	-0.8	-1.5	V
Serial Data Output Voltage	V _{OUT(1)}	I _{OUT} = -200 μA	2.8	3.05	_	4.5	4.75	_	V
	V _{OUT(0)}	I _{OUT} = 200 μA	_	0.15	0.3	_	0.15	0.3	V
Maximum Clock Frequency	f _c		10*	_	_	10*	_	_	MHz
Logic Supply Current	I _{DD(1)}	All Outputs High	_	0.25	0.75	_	0.3	1.0	mA
	I _{DD(0)}	All Outputs Low	-	0.25	0.75	_	0.3	1.0	mA
Load Supply Current	I _{BB(1)}	All Outputs High, No Load	_	3.0	6.0	_	3.0	6.0	mA
	I _{BB(0)}	All Outputs Low	_	0.2	20	_	0.2	20	μA
Blanking-to-Output Delay	t _{dis(BQ)}	C _L = 30 pF, 50% to 50%	_	0.7	2.0	_	0.7	2.0	μs
	t _{en(BQ)}	C _L = 30 pF, 50% to 50%	_	1.8	3.0	_	1.8	3.0	μs
Strobe-to-Output Delay	t _{p(STH-QL)}	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	_	0.7	2.0	_	0.7	2.0	μs
	t _{p(STH-QH)}	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	_	1.8	3.0		1.8	3.0	μs
Output Fall Time	t _f	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	2.4	_	12	2.4	_	12	μs
Output Rise Time	t _r	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	2.4	_	12	2.4	_	12	μs
Output Slew Rate	dV/dt	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	4.0	_	20	4.0	_	20	V/µs
Clock-to-Serial Data Out Delay	t _{p(CH-SQX)}	I _{OUT} = ±200 μA	_	50	_	_	50	_	ns

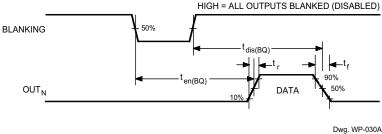
Negative current is defined as coming out of (sourcing) the specified device terminal.

Typical data is is for design information only and is at T_A = +25°C.

^{*} Operation at a clock frequency greater than the specified minimum is possible but not warranteed.

TIMING REQUIREMENTS and SPECIFICATIONS (Logic Levels are V_{DD} and Ground)





A. Data Active Time Before Clock Pulse
(Data Set-Up Time), t _{su(D)} 25 ns
B. Data Active Time After Clock Pulse
(Data Hold Time), t _{h(D)}
$\textbf{C. Clock Pulse Width, } t_{w(CH)} \textbf{50 ns}$
D. Time Between Clock Activation and Strobe, $t_{\text{su}(C)}$ 100 ns
E. Strobe Pulse Width, $t_{w(STH)}$ 50 ns
NOTE – Timing is representative of a 10 MHz clock. Higher
speeds may be attainable with increased supply voltage; op-
eration at high temperatures will reduce the specified maximum

Serial Data present at the input is transferred to the shift register on the logic "0" to logic "1" transition of the CLOCK input pulse. On succeeding CLOCK pulses, the registers shift

clock frequency.

data information towards the SERIAL DATA OUTPUT. The SERIAL DATA must appear at the input prior to the rising edge of the CLOCK input waveform.

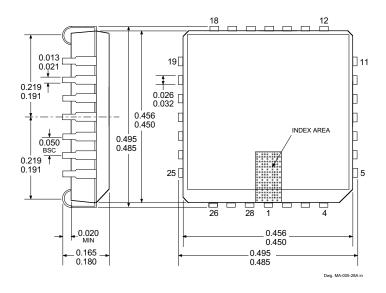
Information present at any register is transferred to the respective latch when the STROBE is high (serial-to-parallel conversion). The latches will continue to accept new data as long as the STROBE is held high. Applications where the latches are bypassed (STROBE tied high) will require that the BLANKING input be high during serial data entry.

When the BLANKING input is high, the output source drivers are disabled (OFF); the pnp active pull-down sink drivers are ON. The information stored in the latches is not affected by the BLANKING input. With the BLANKING input low, the outputs are controlled by the state of their respective latches.

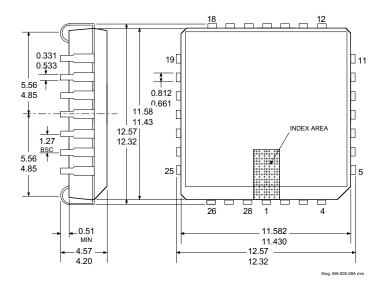


EP Package

Dimensions in Inches (controlling dimensions)



Dimensions in Millimeters (for reference only))



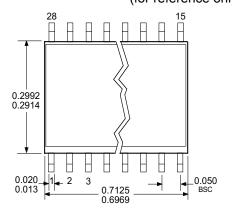
NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.

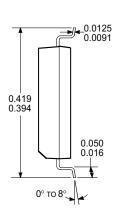
2. Lead spacing tolerance is non-cumulative.

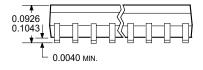


LW Package

Dimensions in Inches (for reference only)

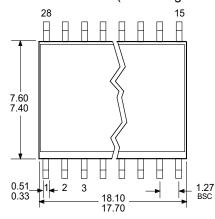


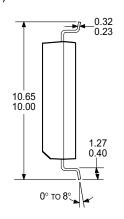


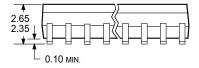


Dwg. MA-008-28A in

Dimensions in Millimeters (controlling dimensions)







Dwg. MA-008-28A mm

NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.

2. Lead spacing tolerance is non-cumulative.

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